Wiring, Printed - Component



COMPANY

CIRCUITOS IMPRESOS 2CI S L Pol Ind La Ferreria La Tecnica 4 Montcada I Reixac, Barcelona 08110 Spain

E325150

	Cond Width				Max	Report						Max			
		Min	Cond	SS/	Area	date	Surface	Assembl	y Solder	Solder		Oper		Meets	C
	Min	Edge	Thk	DS/	Diam	After	Mount	Process	Process	Limits		Temp	Flame	UL796	Т
Туре	mm	mm	mic	DSO	mm	2022-01-01	Technology	Temp °C	Cycles	°C	sec	°C	Class	DSR	I
Multilayer printed wiring boards															
ML	0.11	0.11	14 Int:70	DS	50.8	No	-	-	-	280	20	105	V-0	All	*
ML1 (ASP 1) (Note)	0.11	0.11	14 Int:70	DS	50.8	Yes	Yes	260	6	280	20	130	V-0	All	*
Single layer metal base printed wiring boards															
AL	0.11	0.11	35	SS	50.8	No	-	-	-	288	20	130	V-0	All	0
Single layer printed wiring boards															
DS	0.09	0.09	17	DS	50.8	-	-	-	-	280	20	105	V-0	All	*
DS1 (ASP 1)	0.09	0.09	17	DS	50.8	Yes	Yes	260	6	280	20	130	V-0	All	*
DS2 (ASP 1) (Note)	0.11	0.11	14	DS	50.8	Yes	Yes	260	6	280	20	130	V-0	All	*

^{* -} CTI marking is optional and may be marked on the printed wiring board.

(Note) - Minimum external copper is derived from a minimum of 18 microns foil which is etched down to 14 microns.

ASP 1 - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation



Marking: Company name or tradename "E325150" or trademark or trademark

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